SH SeriesGas Discharge Tubes









Additional Information



Resources





Accessories

Samples

Agency Approvals

Agency	Agency File Number
71 2	E128662

Two Electrode GDT Graphical Symbol



Description

The Littelfuse SH Gas Discharge Tubes (GDT) series provides high levels of protection against fast rising transients caused by lightning disturbances. It has a surge rating of 5kA, 8/20µs. Offered in a Squared Surface Mount package, which helps to make pick and place on PCB process easier.

This GDT series is perfectly suited for broadband equipment applications. The GDT's low off-state capacitance is compatible with high bandwidth applications and this capacitance loading value does not vary if the voltage across the GDT changes.

The Littelfuse SH Gas Discharge Tube (GDT) series are specifically designed for protection of electrical, multimedia, and communication equipment against over voltage transients in surface mount assembly applications.

Features

- Excellent response to fast rising transients
- GHz working frequency
- 5kA, 8/20µs surge capability as defined by IEC 61000-4-5 2nd Edition
- UL Recognized
- Offered with squared body package
- Non-Radioactive
- Ultra Low capacitance (<0.7pF)
- Lead-free and RoHS compliant

Applications

- CATV equipment
- Antennas
- RS 485
- Telecom Base Station
- Power Supply AC Main
- G.fast
- EV power Charging
- Inverter/Variable Frequency Drivers (VFDs)
- IEEE 802.3 compliant Ethernet interfaces
- Broad Band equipment
- xDSL, ADSL, ADSL2, VDSL, and VDSL2
- Medical Electronics
- Test Equipment
- General Telecom Equipment
- Renewable Energy

Electrical Characteristics

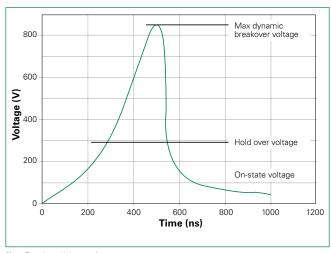
	Component Specifications (at 25°C)							Life Ratings									
Part Number	DC Breakdown in Volts Imp		imum oulse -down tage	Maximum Impulse Discharge Current (8/20µs)	Inculation tai	Capaci- tance (@1MHz)	Impulse Discharge Current (8/20µs)	AC Dischage Current (50Hz, 1sec)	AC Dischage Current (9 Cycles @50Hz)	DC Holdover Voltage (<150ms)*	Impulse Life (10/1000µs) (100A)						
	MIN	TYP	MAX	@100V/ μs	1000V/μs	1 Time	MIN	MAX	MAX	MIN	MIN		MIN				
SH75	60	75	90	600	700	1GΩ @50V 6kA 1GΩ @100V					1GΩ					52V	
SH90	72	90	108	600	700				@50V					52V			
SH145	116	145	174	600	700						10 Shots			52V			
SH230	186	230	276	600	700					@			80V				
SH250	200	250	300	600	700		1GΩ	0.7pf	(5kA)	5A	15A	135V	300				
SH300	240	300	360	650	800		@100V	0.701		5A	IDA	135V	Shots				
SH350	280	350	420	750	900				1 Shot at			135V					
SH400	360	400	480	850	1000					6kA**			135V				
SH470	376	470	564	900	1100			1GΩ					135V				
SH600	480	600	720	1000	1200		@250V					135V					

Note:

Product Characteristics

Materials	Device Tin Plated 3 -15 Microns Construction: Ceramic Insulator		
Storage and Operational Temperature	-40 to +90°C		

Voltage Vs. Time Characteristic



Note: Tested per 1kV/µs waveform

Typical Insertion Loss

@1.0GHz = 0.08dB
@1.4GHz = 0.16dB
@1.8GHz = 0.26dB
@2.0GHz = 0.33dB
@2.4GHz = 0.47dB
@2.8GHz = 0.59dB
@3.1GHz = 0.70dB
@3.5GHz = 0.89dB
@4.0GHz = 1.24dB

Note: Insertion data for customer reference only, application testing needed for verification.



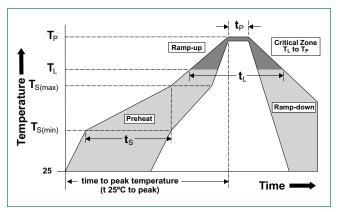
 $^{^{\}star}$ Reference REA PE-80, 0.2A, tested to ITU-T Rec K.12 and REA PE 80 <150 ms.

^{**} DC spark-over may exceed \pm 25% after discharge, but will continue to protect without venting

SH SeriesGas Discharge Tubes

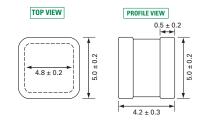
Soldering Parameters - Reflow Soldering (Surface Mount Devices)

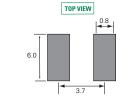
Reflow Condition Pb – Free assembly 150°C Pre Heat Temperature Min (T _{s(min)}) 200°C Time (Min to Max) (t _s) Average ramp up rate (Liquidus Temp (T _L) to peak T _{s(max)} to T _L - Ramp-up Rate Temperature (T _L) (Liquidus) Temperature (t _L) Peak Temperature (T _P) Time within 5°C of actual peak Temperature (t _P) Ramp-down Rate Time 25°C to peak Temperature (T _P) Po not exceed Pre Heat -Temperature Min (T _{s(min)}) 5°C (Second max 217°C 60 – 150 seconds 10 – 30 seconds 8 minutes Max. Po not exceed					
Pre Heat -Temperature Max ($T_{s(max)}$) -Time (Min to Max) (t_s) Average ramp up rate (Liquidus Temp (T_L) to peak $T_{s(max)}$ to T_L - Ramp-up Rate -Temperature (T_L) (Liquidus) -Temperature (T_L) -T	Reflow Condition		Pb – Free assembly		
-Time (Min to Max) (t _s) 60 – 180 secs Average ramp up rate (Liquidus Temp (T _L) to peak T _{s(max)} to T _L - Ramp-up Rate -Temperature (T _L) (Liquidus) 217°C -Temperature (t _l) 60 – 150 seconds Peak Temperature (T _p) 260+0/-5 °C Time within 5°C of actual peak Temperature (t _p) 10 – 30 seconds Ramp-down Rate 6°C/second max Time 25°C to peak Temperature (T _p) 8 minutes Max.		- Temperature Min (T _{s(min)})	150°C		
	Pre Heat	-Temperature Max (T _{s(max)})	200°C		
$ \begin{array}{llllllllllllllllllllllllllllllllllll$		-Time (Min to Max) (t _s)	60 – 180 secs		
$ \begin{array}{c} \textbf{Reflow} & \begin{array}{c} \textbf{-Temperature (T_L) (Liquidus)} & 217^{\circ}\text{C} \\ \hline \textbf{-Temperature (t_L)} & 60-150 \text{ seconds} \\ \end{array} \\ \textbf{Peak Temperature (T_p)} & 260^{+0/5} ^{\circ}\text{C} \\ \hline \textbf{Time within 5°C of actual peak Temperature (t_p)} & 10-30 \text{ seconds} \\ \hline \textbf{Ramp-down Rate} & 6^{\circ}\text{C/second max} \\ \hline \textbf{Time 25°C to peak Temperature (T_p)} & 8 \text{ minutes Max.} \\ \end{array} $	_	np up rate (Liquidus Temp (T _L) to	3°C/second max		
Reflow-Temperature (t_L) $60 - 150 \text{ seconds}$ Peak Temperature (T_p) $260^{+0/-5} ^{\circ}\text{C}$ Time within 5°C of actual peak Temperature (t_p) $10 - 30 \text{ seconds}$ Ramp-down Rate $6^{\circ}\text{C/second max}$ Time 25°C to peak Temperature (T_p) 8 minutes Max	T _{S(max)} to T _L -	Ramp-up Rate	5°C/second max		
-Temperature (t_l) 60 – 150 seconds Peak Temperature (T_p) 260+0/-5 °C Time within 5°C of actual peak Temperature (t_p) 10 – 30 seconds Ramp-down Rate 6°C/second max Time 25°C to peak Temperature (T_p) 8 minutes Max.	Poflow	-Temperature (T _L) (Liquidus)	217°C		
Time within 5°C of actual peak Temperature (t _p) 10 – 30 seconds Ramp-down Rate 6°C/second max Time 25°C to peak Temperature (T _p) 8 minutes Max.	nellow	- Temperature (t _L)	60 – 150 seconds		
(t _p) 10 – 30 seconds Ramp-down Rate 6°C/second max Time 25°C to peak Temperature (T _p) 8 minutes Max.	Peak Tempe	rature (T _P)	260 ^{+0/-5} °C		
Time 25°C to peak Temperature (T _p) 8 minutes Max.		n 5°C of actual peak Temperature	10 – 30 seconds		
р	Ramp-dowr	n Rate	6°C/second max		
Do not exceed 260°C	Time 25°C t	o peak Temperature (T _p)	8 minutes Max.		
	Do not exce	ed	260°C		



Product Dimensions

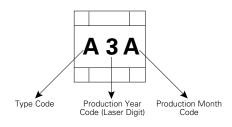
Dimensions in millimeters





Recommended Soldering Pad Layout

Product Marking

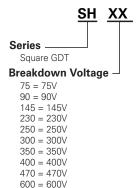


Type Code					
Α	SH75				
В	SH90				
S	SH145				
D	SH230				
R	SH250				
E	SH300				
G	SH350				
I	SH400				
Р	SH470				
V	SH600				

Month Code					
Α	January				
В	February				
С	March				
D	April				
E	May				
F	June				
G	July				
Н	August				
1	September				
J	October				
K	November				
L	December				



Part Numbering System and Ordering Information

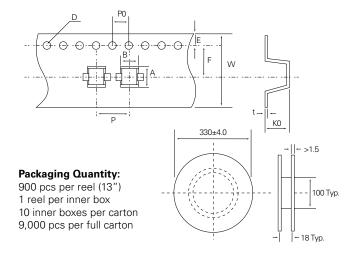


Taping and Reel Specifications

Taping

Unit = mm

Item	Spec	Item	Spec
Р	12.0±0.1	D	Ø1.55±0.05
P0	4.0±0.1	W	16.0±0.3
Α	5.4±0.1	K0	5.4±0.1
В	4.6±0.1	t	0.5±0.05



Disclaimer Notice - Information furnished is believed to be accurate and reliable. However, users should independently evaluate the suitability of and test each product selected for their own applications. Littelfuse products are not designed for, and may not be used in, all applications. Read complete Disclaimer Notice at: www.littelfuse.com/disclaimer-electronics.

